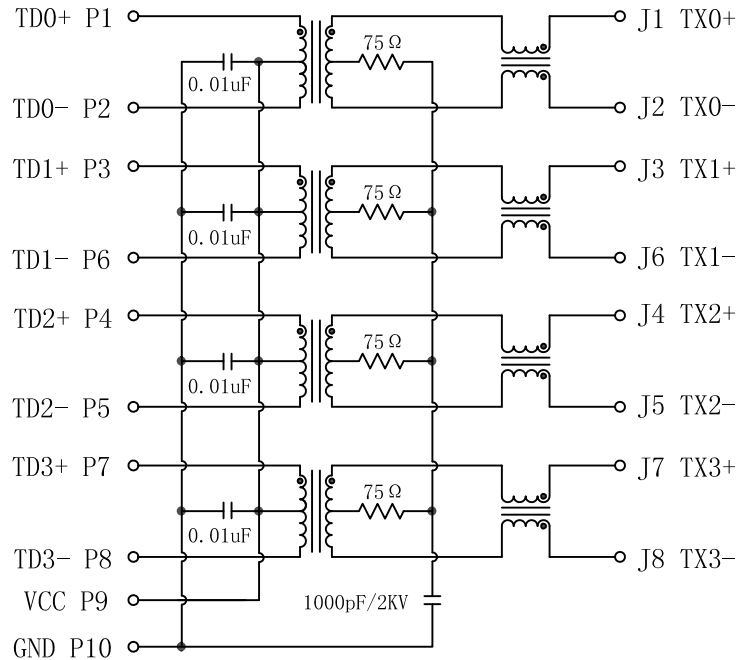


REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2014-06-19	

PC BOARD CONNECTIONS



RJ45 CONNECTOR

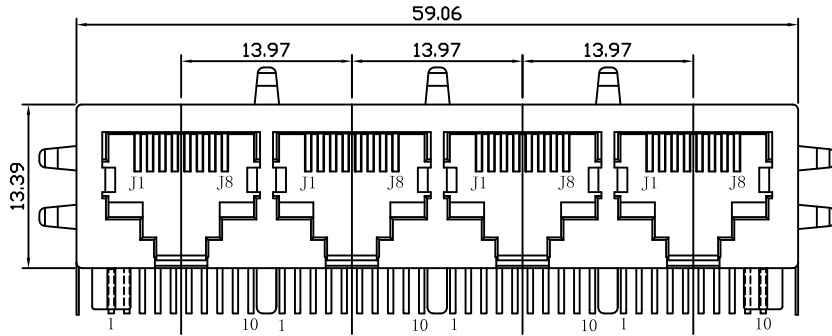
ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio ($\pm 2\%$):
TX=1CT:1CT RX=1CT:1CT
- Inductance OCL: 350uH MIN
@100KHz/0.1V, 8mA DC Bias
- DCR: 1.2 Ω MAX
- Insertion Loss:
-1.0dB MAX @1-65MHz
- Return Loss:
-20dB MIN @1-10MHz
-16dB MIN @10-30MHz
-12dB MIN @30-60MHz
-10dB MIN @60-100MHz
- Cross talk:
-40dB MIN @1-30MHz
-35dB MIN @30-60MHz
-30dB MIN @60-100MHz
- Common Mode Rejection:
-30dB MIN @1-50MHz
-20dB MIN @50-150MHz
- Hipot Test: 1500Vrms MIN
- Operating Temperature Range: 0°C ~ 70°C.

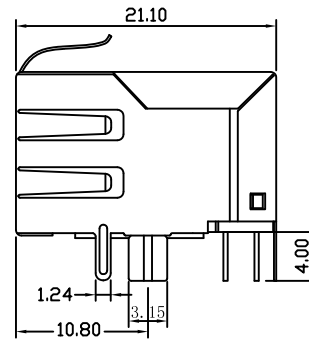


X:X	± 0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX	± 0.25	CHKD:	
X:XXX	± 0.05	DR: TOM	TITLE: RJ45 1x4 Tab-Down Jack With 1000 Base-TX Magnetic Modules
ANGLES	$\pm 1^\circ$	UNIT: mm	PART NO.: LPJGF46813CNL
	SCALE: 2/1	SHEET: 1/2	REV: A DWG NO.: TRC16071318

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2014-06-19	



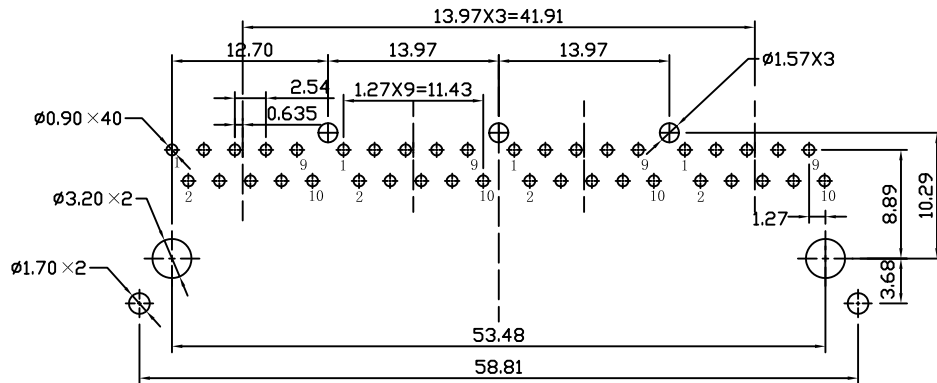
Front Side View



Left Side View



Top Side View



Suggested PCB Layout (Top View)

NOTES:

1. Meets IEEE 802.3 specification
2. Connector Materials:
 Housing Material: Thermoplastic PA46+30%G.F UL94V-0
 Contact Material: Phosphor Bronze C5210R-EH Thickness=0.35mm
 Pins: Brass C2680R-H Thickness=0.35mm
 Shield: Copper alloy Brass H65Y Thickness=0.2mm
 Contact plating: Gold 6 micro-inches min. In contact area.
3. Wave solder tip temperature: 265°C Max, 5 Sec.
4. UL Certification: File Number E484635.



X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX	±0.25	CHKD:	
X:XXX	±0.05	DR: TOM	TITLE: RJ45 1×4 Tab-Down Jack With 1000 Base-TX Magnetic Modules
ANGLES	±1°	UNIT: mm	PART NO.: LPJGF46813CNL
	SCALE: 2/1	SHEET: 2/2	REV: A DWG NO.: TRC16071318